

5N404389929

Abstract of the Disclosure

5 A circuit assembly for fabricating an air bridge structure and a method of
fabricating an integrated circuit package capable of supporting a circuit assembly
including an air bridge structure. A circuit assembly comprises an electronic chip and a
conductive structure embedded in a plurality of materials having a plurality of
vaporization temperatures. The plurality of materials is formed on the electronic chip and
the conductive structure is coupled to the electronic chip. To fabricate the circuit
assembly, a support structure, including interstices, is formed on an electronic chip. The
interstices of the support structure are filled with a material having a vaporization
10 temperature that is less than the vaporization temperature of the support structure.
Conductive structures are embedded in the support structure and the material, and a
connective structure is mounted on the support structure. Finally, the material is removed
from the interstices by heating the circuit assembly.

"Express Mail" mailing label number: EL25461811045

Date of Deposit: August 25, 1999
I hereby certify that this paper or fee is being deposited with the
United States Postal Service "Express Mail Post Office to Addressee"
service under 37 CFR 1.10 on the date indicated above and is
addressed to the Assistant Commissioner for Patents,
Washington, D.C. 20231

Printed Name Chris Hammond

Signature Chris Hammond

09382929 "082999